

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-8. (Canceled)

9. (Currently Amended) ~~An IC label comprising a contactless thin film~~ A flexible integrated circuit capable of performing data transmission wirelessly, comprising:
~~wherein the thin film integrated circuit comprises:~~
a flexible substrate;
an adhesive over the flexible substrate;
a metal oxide over the adhesive;
an insulating film over the metal oxide;
a semiconductor film provided over the insulating film;
a gate electrode provided over the semiconductor film with a gate insulating film interposed between the semiconductor ~~[[layer]]~~ film and the gate electrode; and
an antenna formed from the same material as the gate electrode,
wherein the antenna is formed on and in contact with the gate insulating film.

10. (Canceled)

11. (Currently Amended) ~~An IC label~~ A flexible integrated circuit according to claim 9, wherein the antenna comprises a conductive paste.

12. (Currently Amended) ~~An IC label comprising a contactless thin film~~ A flexible integrated circuit capable of performing data transmission wirelessly, comprising:
~~wherein the thin film integrated circuit comprises:~~

a substrate;
an adhesive over the substrate;
a metal oxide over the adhesive;
an insulating film over the metal oxide;
a transistor comprising a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;
an interlayer insulating film over the transistor;
a wiring formed on the interlayer insulating film, wherein the wiring is connected to an impurity region of the semiconductor film; and
an antenna formed on the interlayer insulating film.

13. (Currently Amended) ~~An IC label~~ A flexible integrated circuit according to claim 12, wherein the antenna comprises a same material as the wiring.

14. (Currently Amended) ~~An IC label~~ A flexible integrated circuit according to claim 12, wherein the antenna comprises a conductive paste.

15.-19. (Canceled)

20. (Currently Amended) A container comprising a ~~contactless thin film~~ flexible integrated circuit capable of performing data transmission wirelessly, wherein the ~~thin film~~ flexible integrated circuit comprises:
a flexible substrate;
an adhesive over the flexible substrate;
a metal oxide over the adhesive;
an insulating film over the metal oxide;
a semiconductor film provided over the insulating film;

a gate electrode that is provided over the semiconductor film with a gate insulating film interposed between the semiconductor ~~[[layer]]~~ film and the gate electrode; and

an antenna formed from the same material as the gate electrode,
wherein the antenna is formed on and in contact with the gate insulating film.

21. (Currently Amended) A container according to claim 20, wherein the ~~thin~~ film flexible integrated circuit is covered by a label.

22. (Currently Amended) A container according to claim 21, wherein a protective film having a DLC film or a CN film is provided between the ~~thin-film~~ flexible integrated circuit and the label.

23. (Currently Amended) A container according to claim 20, wherein the ~~thin~~ film flexible integrated circuit is held between a first label and a second label, and the second label is affixed to the ~~thin-film~~ flexible integrated circuit with an adhesive agent.

24. (Currently Amended) A container comprising a ~~contactless-thin-film~~ flexible integrated circuit capable of performing data transmission wirelessly,

wherein the ~~thin-film~~ flexible integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a transistor comprising a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;

an interlayer insulating film over the transistor;

a wiring provided on the interlayer insulating film; and

an antenna provided on the interlayer insulating film.

25. (Currently Amended) A container according to claim 24, wherein the ~~thin~~ film flexible integrated circuit is covered by a label.

26. (Currently Amended) A container according to claim 25, wherein a protective film having a DLC film or a CN film is provided between the ~~thin-film~~ flexible integrated circuit and the label.

27. (Currently Amended) A container according to claim 24, wherein the ~~thin~~ film flexible integrated circuit is held between a first label and a second label, and the second label is affixed to the ~~thin-film~~ flexible integrated circuit with an adhesive agent.

28.-62. (Canceled)

63. (New) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit disposed over a substrate, the integrated circuit comprising thin film transistors,
wherein the substrate has a flexibility.

64. (New) The flexible integrated circuit according to claim 63 wherein the substrate is a plastic substrate.

65. (New) The flexible integrated circuit according to claim 63 each of the thin film transistors includes a semiconductor film comprising silicon.

66. (New) The flexible integrated circuit according to claim 63 further comprising an antenna electrically connected to the integrated circuit.

67. (New) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit attached to a substrate with an adhesive interposed therebetween, the integrated circuit comprising thin film transistors, wherein the substrate has a flexibility.

68. (New) The flexible integrated circuit according to claim 67 wherein the substrate is a plastic substrate.

69. (New) The flexible integrated circuit according to claim 67 each of the thin film transistors includes a semiconductor film comprising silicon.

70. (New) The flexible integrated circuit according to claim 67 further comprising an antenna electrically connected to the integrated circuit.

71. (New) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit disposed over a substrate, the integrated circuit comprising thin film transistors; and

an antenna formed over the substrate, wherein the substrate has a flexibility.

72. (New) The flexible integrated circuit according to claim 71 wherein the substrate is a plastic substrate.

73. (New) The flexible integrated circuit according to claim 71 each of the thin film transistors includes a semiconductor film comprising silicon.

74. (New) The flexible integrated circuit according to claim 71 further comprising a wiring electrically connected to the integrated circuit wherein the wiring and the antenna are formed on a same surface.

75. (New) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit attached to a substrate with an adhesive interposed therebetween, the integrated circuit comprising thin film transistors, and

an antenna formed over the substrate,

wherein the substrate has a flexibility.

76. (New) The flexible integrated circuit according to claim 75 wherein the substrate is a plastic substrate.

77. (New) The flexible integrated circuit according to claim 75 each of the thin film transistors includes a semiconductor film comprising silicon.

78. (New) The flexible integrated circuit according to claim 75 further comprising a wiring electrically connected to the integrated circuit wherein the wiring and the antenna are formed on a same surface.

79. (New) A flexible integrated circuit capable of performing data transmission wirelessly, comprising:

an integrated circuit including a memory disposed over a substrate, the integrated circuit comprising thin film transistors,

wherein the substrate has a flexibility.

80. (New) The flexible integrated circuit according to claim 79 wherein the substrate is a plastic substrate.

81. (New) The flexible integrated circuit according to claim 79 each of the thin film transistors includes a semiconductor film comprising silicon.

82. (New) The flexible integrated circuit according to claim 79 further comprising an antenna electrically connected to the integrated circuit.

83. (New) The flexible integrated circuit according to claim 79 wherein the memory is a rewritable memory.

84. (New) The flexible integrated circuit according to claim 79 wherein the integrated circuit is attached to the substrate with an adhesive interposed therebetween.

85. (New) A system comprising:
a cellular phone having a reading function; and
a flexible integrated circuit capable of performing data transmission wirelessly, the flexible integrated circuit comprising an integrated circuit including a memory disposed over a substrate, the integrated circuit comprising thin film transistors, wherein the substrate has a flexibility,
wherein the cellular phone is capable of receiving information from the flexible integrated circuit wirelessly.

86. (New) The flexible integrated circuit according to claim 85 wherein the substrate is a plastic substrate.

87. (New) The flexible integrated circuit according to claim 85 each of the thin film transistors includes a semiconductor film comprising silicon.

88. (New) The flexible integrated circuit according to claim 85 further comprising an antenna electrically connected to the integrated circuit.